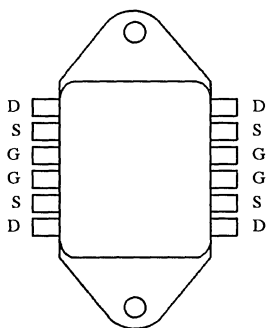


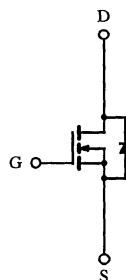
Four N-Channel Enhancement-Mode Transistors

Product Summary

$V_{(BR)DSS}$ (V)	$r_{DS(on)}$ (Ω)	I_D (A)
100	0.08	21



Leadform Options
 MOD100B ... Bent Down
 MOD100C ... Bent Up



N-Channel MOSFET

Absolute Maximum Ratings ($T_C = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Single Die	All Die	Unit
Drain-Source Voltage	V_{DS}	100	100	V
Gate-Source Voltage	V_{GS}	± 20	± 20	
Continuous Drain Current ($T_J = 150^\circ\text{C}$)	I_D	$T_C = 25^\circ\text{C}$	21	A
		$T_C = 100^\circ\text{C}$	21	
Pulsed Drain Current	I_{DM}	125	440	W
Avalanche Current (See Thermal Ratings)	I_A	21		
Maximum Power Dissipation	P_D	$T_C = 25^\circ\text{C}$	150	W
		$T_C = 100^\circ\text{C}$	60	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 150		$^\circ\text{C}$
Isolation Voltage	V_{ISOL}	1000		V

Thermal Resistance Ratings

Parameter	Symbol	Typical	Single Die	All Die	Unit
Maximum Junction-to-Ambient	R_{thJA}		30	30	$^\circ\text{C/W}$
Maximum Junction-to-Case	R_{thJC}		0.83	0.31	
Case-to-Sink	R_{thCS}	0.1			

Specifications ($T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Limit			Unit
			Min	Typ	Max	
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	100			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\ \text{mA}$	2.0		4.0	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 80\text{ V}, V_{GS} = 0\text{ V}$			250	μA
		$V_{DS} = 80\text{ V}, V_{GS} = 0\text{ V}, T_J = 125^\circ\text{C}$			1000	
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} = 10\text{ V}, V_{GS} = 10\text{ V}$	21			A
Drain-Source On-State Resistance ^a	$r_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 20\text{ A}$		0.070	0.08	Ω
		$V_{GS} = 10\text{ V}, I_D = 20\text{ A}, T_J = 125^\circ\text{C}$		0.100	0.120	
Forward Transconductance ^a	g_{fs}	$V_{DS} = 15\text{ V}, I_D = 20\text{ A}$	9.0	11.0		S
Dynamic						
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$		2800		pF
Output Capacitance	C_{oss}			1100		
Reverse Transfer Capacitance	C_{rss}			400		
Total Gate Charge	Q_g	$V_{DS} = 50\text{ V}, V_{GS} = 10\text{ V}, I_D = 21\text{ A}$		90	125	nC
Gate-Source Charge	Q_{gs}			18	22	
Gate-Drain Charge	Q_{gd}			30	65	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 24\text{ V}, R_L = 1.2\ \Omega$ $I_D \cong 20\text{ A}, V_{GEN} = 10\text{ V}, R_G = 4.7\ \Omega$		15	35	ns
Rise Time	t_r			30	100	
Turn-Off Delay Time	$t_{d(off)}$			50	125	
Fall Time	t_f			20	100	
Source-Drain Diode Ratings and Characteristics						
Continuous Current	I_S				21	A
Pulsed Current	I_{SM}				125	
Diode Forward Voltage ^a	V_{SD}	$I_F = 21\text{ A}, V_{GS} = 0\text{ V}$			2.5	V
Reverse Recovery Time	t_{rr}	$I_F = 21\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$		150		ns
Reverse Recovery Charge	Q_{rr}				0.5	μC

Notes:

- Pulse test; pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$.
- Independent of operating temperature.

Typical Characteristics (25°C Unless Otherwise Noted)

